

STPSC1006

600 V power Schottky silicon carbide diode

Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- Particularly suitable in PFC boost diode function

Description

The SiC diode is an ultrahigh performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide bandgap material allows the design of a Schottky diode structure with a 600 V rating. Due to the Schottky construction no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

ST SiC diodes will boost the performance of PFC operations in hard switching conditions.

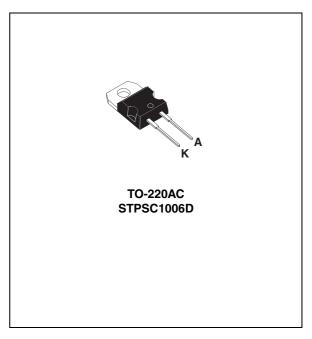


Table 1. Device summary

| | • |
|----------------------|--------|
| I _{F(AV)} | 10 A |
| V_{RRM} | 600 V |
| T _{j (max)} | 175 °C |
| Q _{C (typ)} | 12 nC |

Characteristics STPSC1006

1 Characteristics

Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)

| Symbol | Par | Value | Unit | |
|---------------------|---|---|-------------|----|
| V_{RRM} | Repetitive peak reverse voltage | | 600 | V |
| I _{F(RMS)} | Forward rms current | | 18 | Α |
| I _{F(AV)} | Average forward current $T_c = 115$ °C, $\delta = 0.5$ | | 10 | Α |
| | Surga pap rapatitiva forward | $t_p = 10$ ms sinusoidal, $T_c = 25$ °C | 40 | |
| I _{FSM} | Surge non repetitive forward current | $t_p = 10 \text{ ms sinusoidal, } T_c = 125 ^{\circ}\text{C}$ | 32 | Α |
| | our one | $t_p = 10 \mu s \text{ square}, T_c = 25 ^{\circ}\text{C}$ | 160 | |
| I _{FRM} | Repetitive peak forward current $\delta = 0.1$, $T_C = 110$ °C, $T_j = 150$ °C | | 40 | А |
| T _{stg} | Storage temperature range | | -55 to +175 | °C |
| Tj | Operating junction temperature | | -40 to +175 | °C |

Table 3. Thermal resistance

| Symbol | Parameter | Value | Unit |
|----------------------|------------------|-------|------|
| R _{th(j-c)} | Junction to case | 2 | °C/W |

Table 4. Static electrical characteristics

| Symbol | Parameter | Tests conditions | | Min. | Тур. | Max. | Unit |
|---|-------------------------|-------------------------|-----------------|------|------|------|------|
| I _R ⁽¹⁾ | Reverse leakage | T _j = 25 °C | V - V | - | 30 | 150 | пΛ |
| 'R` | ^{'R} current | T _j = 150 °C | $V_R = V_{RRM}$ | - | 210 | 1500 | μΑ |
| V _F ⁽²⁾ | Forward voltage drop | T _j = 25 °C | - | 1.4 | 1.7 | V | |
| v _F · / Forward voltage drop | T _j = 150 °C | IF = 10 A | - | 1.6 | 2.1 | V | |

^{1.} $t_p = 10 \text{ ms}, \ \delta < 2\%$

To evaluate the conduction losses use the following equation:

 $P = 1.2 \text{ x I}_{F(AV)} + 0.09 \text{ x I}_{F^2(RMS)}$

Table 5. Other parameters

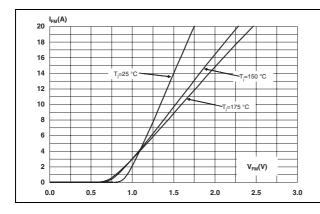
| Symbol | Parameter | Test conditions | Тур. | Unit |
|---------------------|-------------------------|---|------|------|
| Q _c | Total capacitive charge | $V_r = 400 \text{ V}, I_F = 10 \text{ A} \text{ d}I_F/\text{d}t = -200 \text{ A}/\mu\text{s}$ $T_j = 150 ^{\circ}\text{C}$ | 12 | nC |
| С | Total capacitance | $V_r = 0 \text{ V}, T_c = 25 \text{ °C}, F = 1 \text{ Mhz}$ | 650 | pF |
| C Total capacitance | | $V_r = 400 \text{ V}, T_c = 25 ^{\circ}\text{C}, F = 1 \text{ Mhz}$ | 50 | ρг |

^{2.} $t_p = 500 \ \mu s, \ \delta < 2\%$

STPSC1006 Characteristics

Figure 1. Forward voltage drop versus forward current (typical values)

Figure 2. Reverse leakage current versus reverse voltage applied (maximum values)



1.E+04

1.E+03

1.E+02

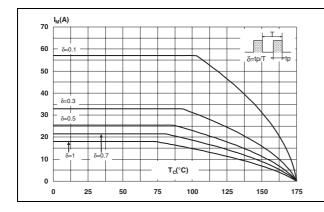
1.E+01

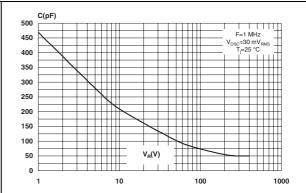
1.E+00

0 50 100 150 200 250 300 350 400 450 500 550 600

Figure 3. Peak forward current versus case temperature

Figure 4. Junction capacitance versus reverse voltage applied (typical values)

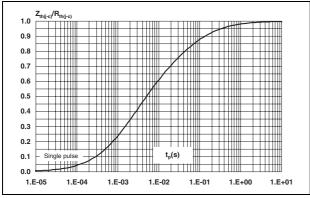




Characteristics STPSC1006

Figure 5. Relative variation of thermal impedance junction to case versus pulse duration

Figure 6. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)



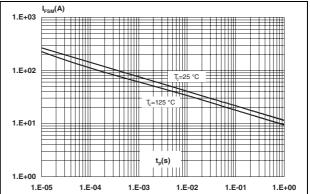
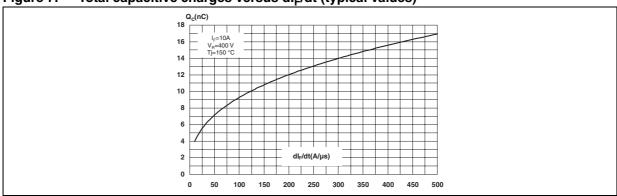


Figure 7. Total capacitive charges versus dl_F/dt (typical values)

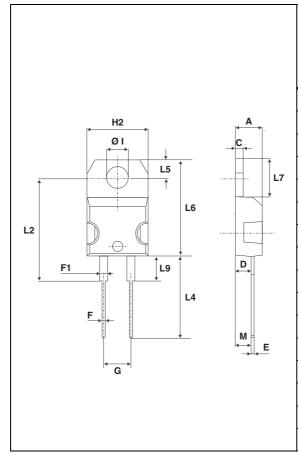


2 Package information

- Epoxy meets UL94, V0
- Cooling method: convection (C)
- Recommended torque value: 0.4 to 0.6 N⋅m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Table 6. TO-220AC Dimensions



| | Dimensions | | | |
|---------|-------------|-------|-------------|--------|
| Ref. | Millimeters | | Inc | hes |
| | Min. | Max. | Min. | Max. |
| Α | 4.40 | 4.60 | 0.173 | 0.181 |
| О | 1.23 | 1.32 | 0.048 | 0.051 |
| D | 2.40 | 2.72 | 0.094 | 0.107 |
| Е | 0.49 | 0.70 | 0.019 | 0.027 |
| F | 0.61 | 0.88 | 0.024 | 0.034 |
| F1 | 1.14 | 1.70 | 0.044 | 0.066 |
| G | 4.95 | 5.15 | 0.194 | 0.202 |
| H2 | 10.00 | 10.40 | 0.393 | 0.409 |
| L2 | 16.40 typ. | | 0.645 typ. | |
| L4 | 13.00 | 14.00 | 0.511 | 0.551 |
| L5 | 2.65 | 2.95 | 0.104 | 0.116 |
| L6 | 15.25 | 15.75 | 0.600 | 0.620 |
| L7 | 6.20 | 6.60 | 0.244 | 0.259 |
| L9 | 3.50 | 3.93 | 0.137 | 0.154 |
| М | 2.6 typ. | | 0.102 | 2 typ. |
| Diam. I | 3.75 | 3.85 | 0.147 0.151 | |

Ordering information STPSC1006

3 Ordering information

 Table 7.
 Ordering information

| Order code | Marking | Package | Weight | Base qty | Delivery mode |
|------------|------------|----------|--------|----------|---------------|
| STPSC1006D | STPSC1006D | TO-220AC | 1.86 g | 50 | Tube |

4 Revision history

Table 8. Document revision history

| Date | Revision | Changes |
|-------------|----------|-------------|
| 24-Sep-2009 | 1 | First issue |

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2009 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

